SCBS084B - D3712, JANUARY 1991 - REVISED DECEMBER 1992

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art EPIC-IIB ™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes **PCB Layout**
- High-Drive Outputs (-32-mA I_{OH}, 64-mA IOI)
- Packaged in Plastic 300-mil Shrink **Small-Outline and Thin Shrink Small-Outline Packages and 380-mil** Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings

description

'ABT16245 is a 16-bit (dual-octal) noninverting 3-state transceiver designed for synchronous two-way communication between data buses. The control function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data

transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to ${\sf V_{CC}}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16245 is available in Ti's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16245 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16245 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE (each 8-bit section)

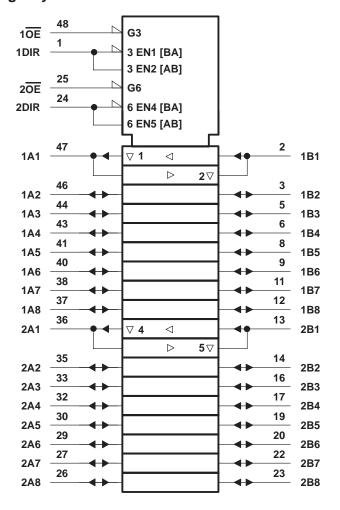
INP	UTS	ODED ATION				
ŌĒ	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				

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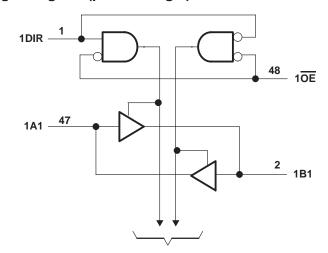
SN54ABT16245 . . . WD PACKAGE SN74ABT16245 . . . DGG OR DL PACKAGE (TOP VIEW)

1				1
1DIR	1	\cup	48	1 <u>0E</u>
1B1 🛚	2		47] 1A1
1B2 🛚	3		46] 1A2
GND [4		45	GND
1B3 🛚	5		44	1A3
1B4 🛚	6		43] 1A4
v _{cc} [7		42	□ v _{cc}
1B5	8		41	1A5
1B6	9		40	1A6
GND	10		39	GND
1B7	11		38	1A7
1B8	12		37	1A8
2B1	13		36	2A1
2B2	14		35	2A2
GND [15		34	GND
2B3	16		33	2A3
2B4	17		32	2A4
V _{CC}	18		31	□ v _{cc}
2B5	19		30	2A5
2B6	20		29	2A6
GND	21		28	GND
2B7 🛚	22		27	2A7
2B8 🛚	23		26	2 <u>A8</u>
2DIR	24		25	2 <mark>0E</mark>
				J

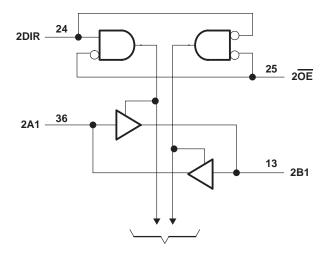
logic symbol†



logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high state or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16245	96 mA
SN74ABT16245	128 mA
Input clamp current, $I_{ K }(V_1 < 0)$	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air): DGG package	0.8 W
DL package	0.85 W
Storage temperature range	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 2)

			SN54AE	T16245	SN74AE	T16245	
			MIN	MAX	MIN	MAX	UNIT
V _{CC} Supply voltage				5.5	4.5	5.5	V
VIH High-level input voltage					2		V
V _{IL}	L Low-level input voltage					0.8	V
٧ _I	/I Input voltage			Vсс	0	VCC	V
loh	IOH High-level output current			-24		-32	mA
loL	OL Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T _A Operating free-air temperature				125	-40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	T-01 00101710110			1	T _A = 25°(С	SN54ABT16245		SN74ABT16245		
PARAMETER	TEST	CONDITION	S	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ m/s}$	١	2.5			2.5		2.5		
.,	V _C C = 5 V,	I _{OH} = -3 m/	١	3			3		3		.,
VOH	V _{CC} = 4.5 V,	I _{OH} = - 24 m	ıA	2			2				V
	$V_{CC} = 4.5 \text{ V},$	I _{OH} = - 32 m	ıA	2‡					2		
V	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 48 mA				0.55		0.55			V
VOL	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 64 mA				0.55‡				0.55	V
	$V_{CC} = 5.5 \text{ V},$	Control inputs			±1		±1		±1		
ıı	$V_{I} = V_{CC}$ or GND		A or B ports			±100		±100		±100	μΑ
I _{OZH} §	$V_{CC} = 5.5 \text{ V},$	$= 5.5 \text{ V}, \qquad \text{V}_{\text{O}} = 2.7 \text{ V}$				10¶		10		10¶	μΑ
lozL§	$V_{CC} = 5.5 \text{ V}, \qquad V_{O} = 0.5 \text{ V}$				-10¶		-10		-10¶	μΑ	
l _{off}	$V_{CC} = 0$,	V _I or V _O ≤ 4.5 V				±100				±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V},$	V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO#	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 V$		-50	-100	-180	-50	-180	-50	-180	mA
	V _{CC} = 5.5 V, I _O = 0,	A or B ports	Outputs high			2		2		2	mA
Icc			Outputs low			32		32		32	
100	$V_I = V_{CC}$ or GND	A or B ports	Outputs disabled			2		2		2	1117
	Other inputs at		Outputs enabled			1		1.5		1	
ΔICC		Data inputs	Outputs disabled			0.05		1		0.05	mA
	V _{CC} or GND	Control inputs				1.5		1.5		1.5	
Ci	V _I = 2.5 V or 0.5 V	= 2.5 V or 0.5 V Control inputs			3						pF
C _{io}	V _O = 2.5 V or 0.5 V		A or B ports		8.5						pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

If This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.



[‡] On products compliant to MIL-STD-883, Class B, this parameter does not apply.

[§] The parameters I_{OZH} and I_{OZL} include the input leakage current.

This data sheet limit may vary among suppliers.

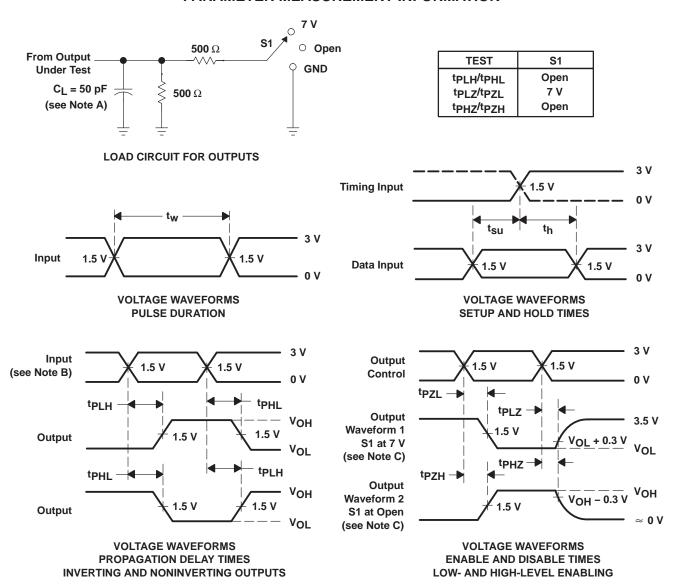
[#] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

SN54ABT16245, **SN74ABT16245 16-BIT BUS TRÁNSCEIVERS** WITH 3-STATE OUTPUTS SCBS084B - D3712, JANUARY 1991 - REVISED DECEMBER 1992

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _C	CC = 5 V 4 = 25°C	', ;	SN54AB	T16245	SN74AB	T16245	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A == B	D an A	1	2.2	3.4	0.5	4	1	3.9	
^t PHL	A or B	B or A	1	2.1	3.8	0.5	4.6	1	4.5	ns
^t PZH	OE	D A	1	3.1	4.4	0.8	5.5	1	5.4	
^t PZL	OE .	B or A	1	3	6.1	0.9	7.3	1	7.2	ns
^t PHZ	. OE	B or A	1.3	3.5	4.7	1.3	6.3	1.3	5.5	ne
t _{PLZ}	OE	BUIA	1.4	3.2	4.7	1.4	5.3	1.4	5.2	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





ti.com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT16245DGGR	OBSOLETE	TSSOP	DGG	48	TBD	Call TI	Call TI
SN74ABT16245DL	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI
SN74ABT16245DLR	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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